

Abstract

In one embodiment, reducing electromagnetic radiation from sources within a substrate, such as a substrate for supporting an integrated circuit die, where the substrate comprises power layers, ground layers, and ground rings surrounding all or a portion of the power layers, where the ground layers and the ground rings are extended at least to the edges of the substrate so that conductive plates may be in electrical contact with the ground layers and the ground rings so as to define an enclosure to substantially contain electromagnetic radiation from sources within the defined enclosure.

Continued on next page